

Product Summary (Typ @ $V_{GS} = -4.5V$, $T_A = +25^\circ C$)

BV_{DSS}	$R_{DS(ON)}$	Q_g	Q_{gd}	I_D
-12V	65m Ω	9nC	2.4nC	-3.2A

Features and Benefits

- Built-in G-S Protection Diode against ESD 2kV HBM
- Ultra Small 0.8mm x 0.8mm Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**
- Qualified to AEC-Q101 Standards for High Reliability**

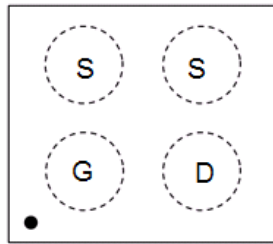
Description and Applications

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications. It is a High performance MOSFET in ultra-small 0.8mm x 0.8mm package.

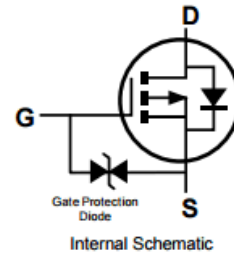
- Portable Applications
- Load Switch
- Power Management Functions

Mechanical Data

- Case: X2-WLB0808-4
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- UBM Opening: 203 μ m

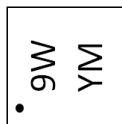


Top View


Ordering Information (Note 4)

Part Number	Case	Packaging
DMP1100UCB4-7	X2-WLB0808-4	3000/Tape & Reel

- Notes:
- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 - See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 - For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


9W = Product Type Marking Code
 YM = Date Code Marking
 Y or \bar{Y} = Year (ex: D = 2016)
 M or \bar{M} = Month (ex: 9 = September)

Date Code Key

Year	2016	2017	2018	2019	2020	2021	2022
Code	D	E	F	G	H	I	J

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-12	V
Gate-Source Voltage	V_{GSS}	± 8	V
Continuous Source Current @ $V_{GS} = -4.5V$ (Note 5)	I_D	$T_A = +25^\circ C$	-2.5
		$T_A = +70^\circ C$	-2.0
Continuous Source Current @ $V_{GS} = -4.5V$ (Note 6)	I_D	$T_A = +25^\circ C$	-3.2
		$T_A = +70^\circ C$	-2.6
Pulsed Drain Current (Pulse Duration 10 μs , Duty Cycle $\leq 1\%$)	I_{DM}	-13	A
Continuous Source-Drain Diode Current	I_S	-1.2	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_D	0.67	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	187	$^\circ C/W$
Total Power Dissipation (Note 6)	P_D	1.1	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	117	$^\circ C/W$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ C$

Electrical Characteristics (@ $T_A = +25^\circ C$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	-12	-	-	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	I_{DSS}	-	-	-1	μA	$V_{DS} = -12V, V_{GS} = 0V$
Gate-Body Leakage	I_{GSS}	-	-	± 10	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	-0.35	-0.55	-0.8	V	$V_{DS} = V_{GS}, I_D = -250\mu A$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	-	65	83	$m\Omega$	$V_{GS} = -4.5V, I_D = -3A$ $V_{GS} = -2.5V, I_D = -2A$ $V_{GS} = -1.8V, I_D = -1A$ $V_{GS} = -1.5V, I_D = -1A$ $V_{GS} = -1.4V, I_D = -1A$ $V_{GS} = -1.3V, I_D = -1A$
			80	96		
			90	150		
			115	170		
			135	300		
150	400					
Forward Transfer Admittance	$ Y_{fs} $	-	6.5	-	S	$V_{DS} = -4V, I_S = -1.5A$
Body Diode Forward Voltage	V_{SD}	-	-0.7	-	V	$V_{GS} = 0V, I_S = -1.5A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	-	680	820	pF	$V_{DS} = -6V, V_{GS} = 0V,$ $f = 1.0MHz$
Output Capacitance	C_{oss}	-	220	290	pF	
Reverse Transfer Capacitance	C_{rss}	-	205	280	pF	
Gate Resistance	R_g	-	11.2	17	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$
Total Gate Charge	Q_g	-	9.0	14	nC	$V_{GS} = -4.5V, V_{DS} = -6V,$ $I_D = -2A$
Gate-Source Charge	Q_{gs}	-	1.0	-	nC	
Gate-Drain Charge	Q_{gd}	-	2.6	-	nC	
Turn-On Delay Time	$t_{D(ON)}$	-	4.4	9	ns	$V_{DD} = -4V, I_D = -2A$ $V_{GEN} = -4.5V, R_g = 1\Omega, R_L = 3\Omega$
Turn-On Rise Time	t_R	-	10.1	-	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	-	22	33	ns	
Turn-Off Fall Time	t_F	-	20	-	ns	

- Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 7. Short duration pulse test used to minimize self-heating effect.
 8. Guaranteed by design. Not subject to production testing.

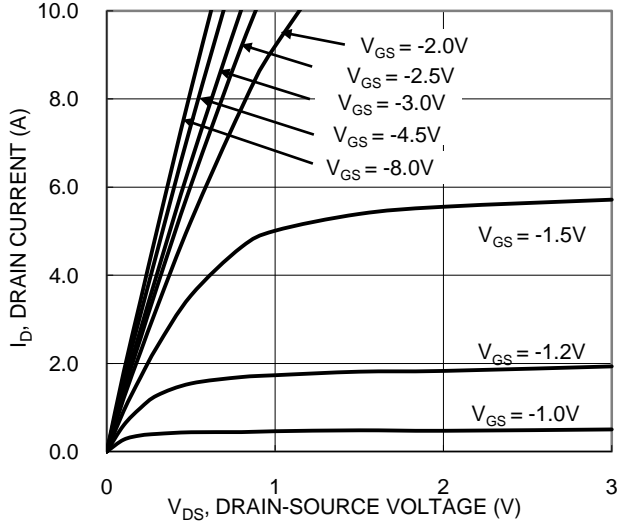


Figure 1. Typical Output Characteristic

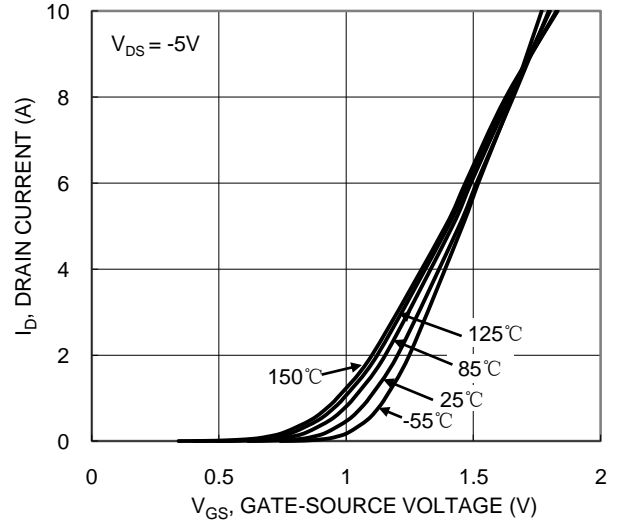


Figure 2. Typical Transfer Characteristic

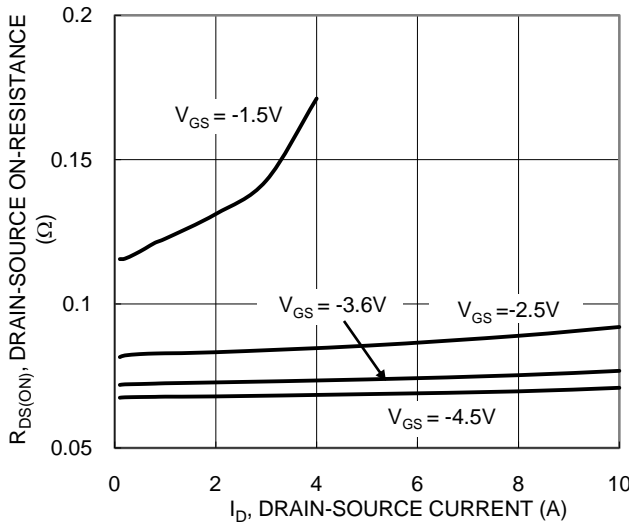


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

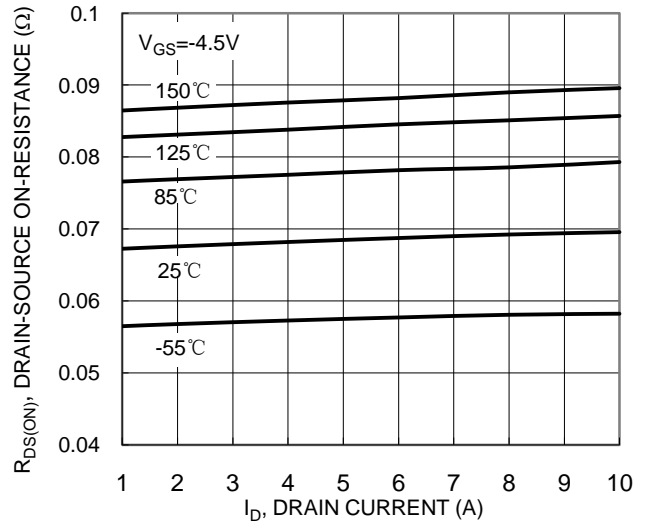


Figure 4. Typical On-Resistance vs. Drain Current and Junction Temperature

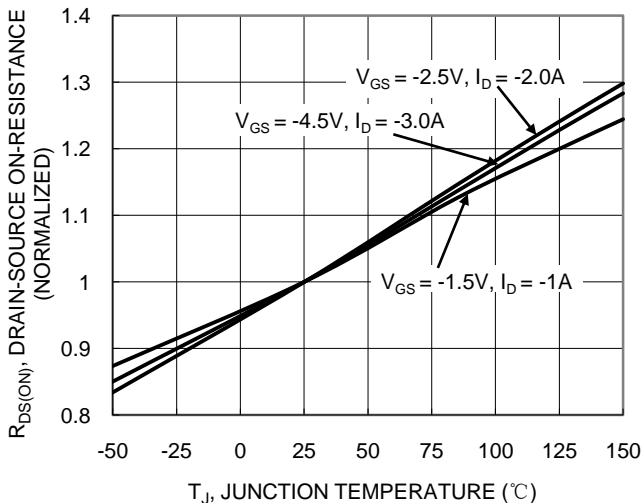


Figure 5. On-Resistance Variation with Junction Temperature

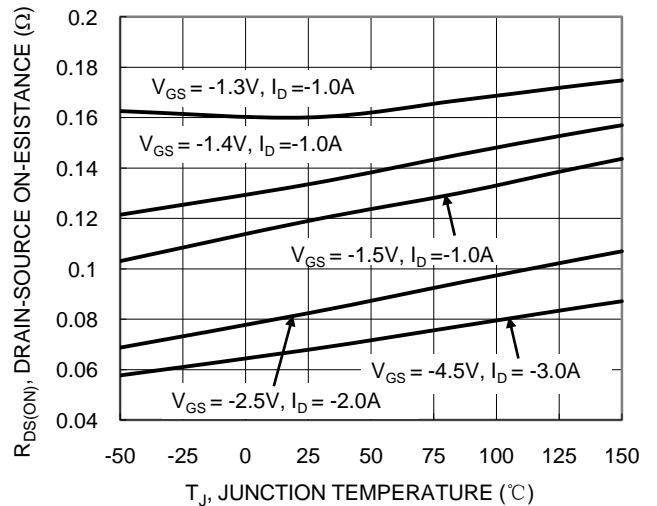


Figure 6. On-Resistance Variation with Junction Temperature

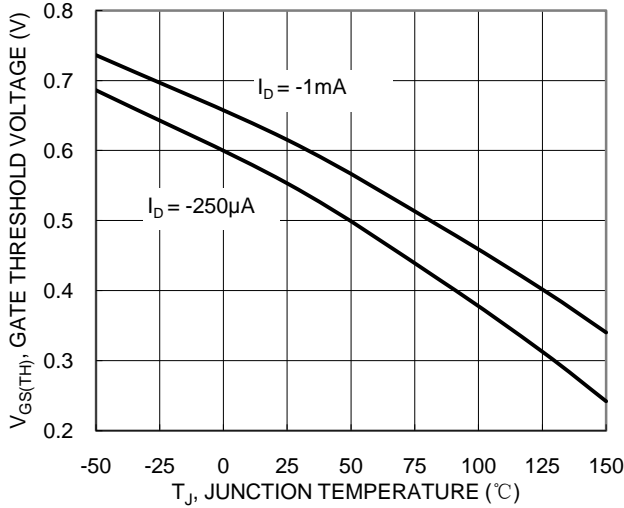


Figure 7. Gate Threshold Variation vs. Junction Temperature

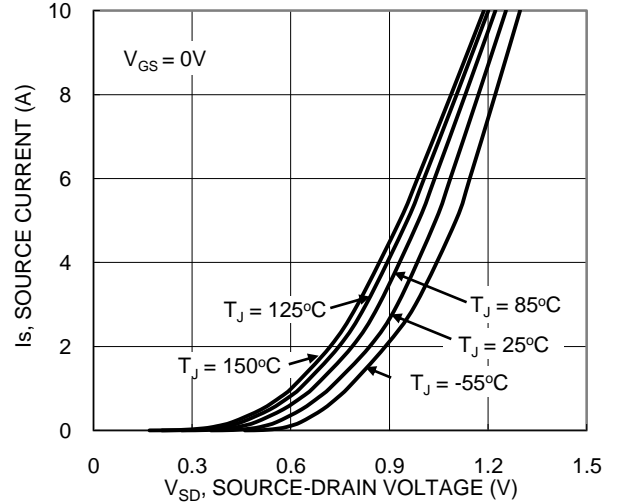


Figure 8. Diode Forward Voltage vs. Current

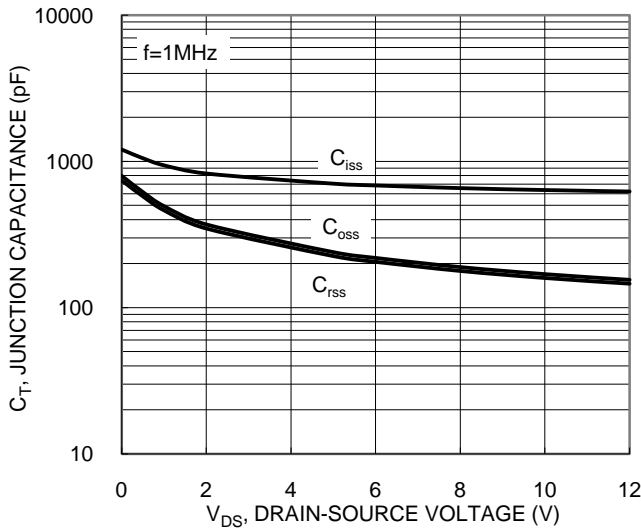


Figure 9. Typical Junction Capacitance

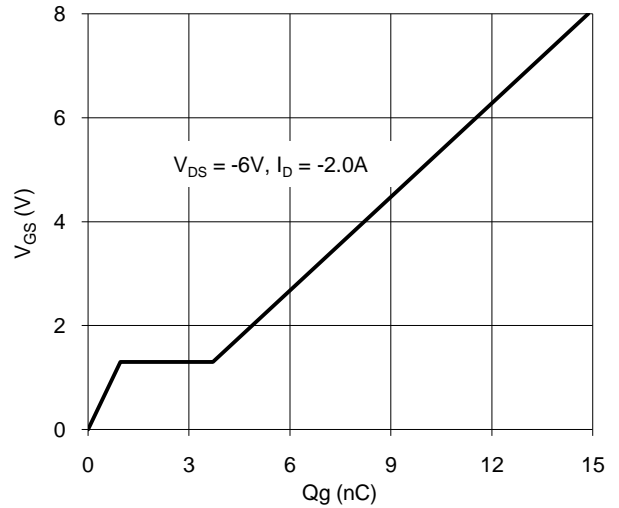


Figure 10. Gate Charge

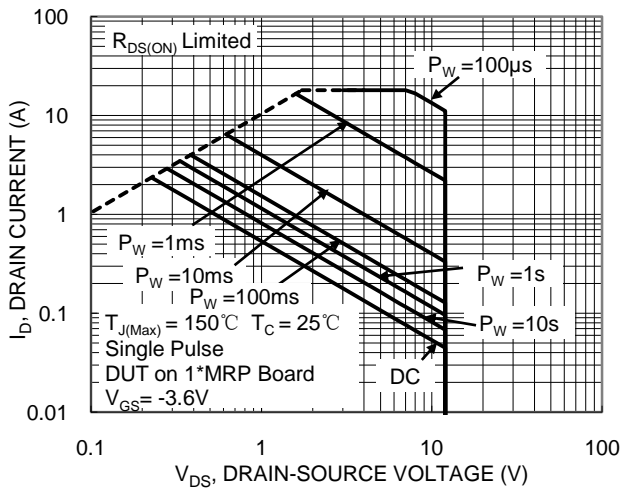


Figure 11. SOA, Safe Operation Area

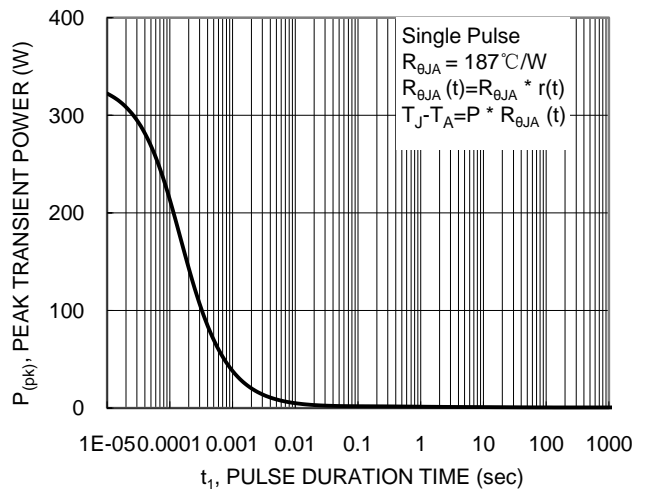


Figure 12. Single Pulse Maximum Power Dissipation

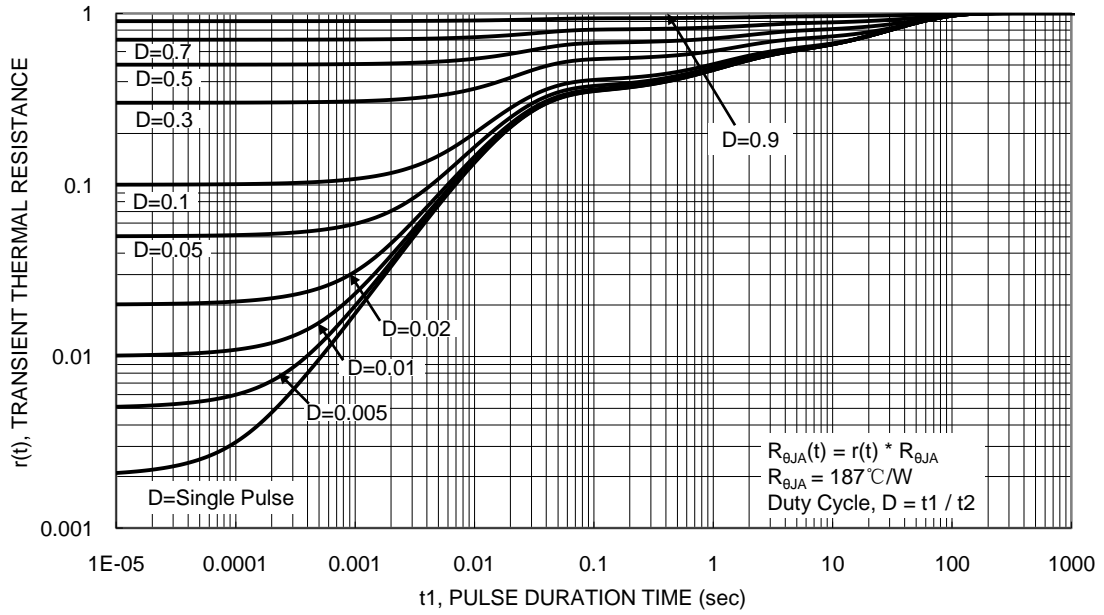
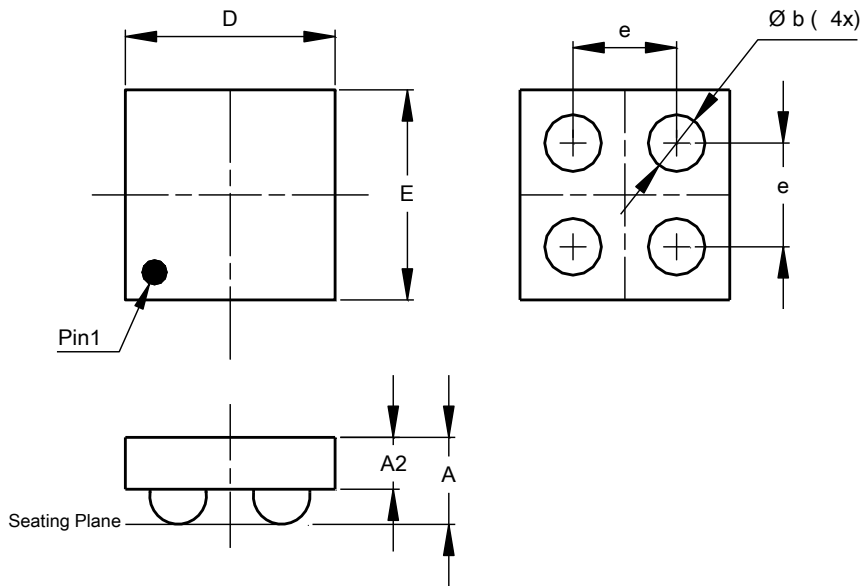


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-WLB0808-4

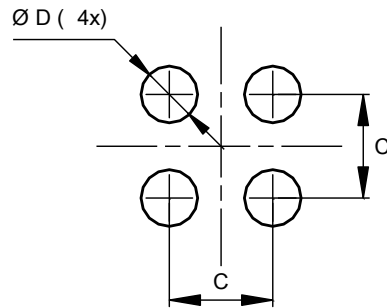


X2-WLB0808-4			
Dim	Min	Max	Typ
A	--	0.375	0.350
A2	--	--	0.200
b	0.1971	0.2409	0.219
D	0.780	0.810	0.800
E	0.780	0.810	0.800
e	--	--	0.400
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-WLB0808-4



Dimensions	Value (in mm)
C	0.400
D	0.219

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